

CC Electronics capabilities

	current production capability	planned production capability
PADS AND HOLES		
through hole size	0.2 mm	0.15 mm
blind/buried hole size	0.12 mm	0.1 mm
plated through hole size tolerance (+/-)	0.1 mm	0.1 mm
non plated hole size tolerance (+/-)	0.05 mm	0.05 mm
hole positional tolerance	0.025 mm	0.0025 mm
through hole pad size (inner) (assume tangency)	0.4 mm	0.3 mm
through hole pad size (outer) (assume tangency)	0.3 mm	0.25 mm
blind/buried pad size	0.25 mm	0.2 mm
press fit hole tolerance (+/-)	0.075 mm	0.05 mm

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PRODUCT DIMENSIONS		
max PCB delivery unit (testable)	559 x 375	559 x 407
min PCB thickness	0.4	0.3
max PCB thickness	3.6	3.6
PCB thickness tolerance	10%	10%
broad flatness (%)	1	1
max layer count	24	24
aspect ratio (0.3mm hole 20um min CU)	8:1	10:1

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INNERLAYERS		
minimum track width & spacing	0.075 mm	0.065 mm
Cu foil thickness (min)	18 um	12 um
Cu foil thickness (max)	105 um	140 um
cores with imbalanced Copper	Y	Y
min dielectric thickness [cores]	0.1 mm	0.075 mm

	current production capability	planned production capability
MICROVIA		
microvias 1 to 2	0.12 mm	0.1 mm
min microvia hole size (drilled)	0.12 mm	0.1 mm
min microvia pad size capture (outer)	0.25 mm	0.2 mm
min microvia pad size bounce (inner)	0.2 mm	0.15 mm
microvia: 1 to 3 and N to [n-2]	0.25 mm	0.2 mm
microvia: filling of vias (plated Cu)	Y	Y

	current production capability	planned production capability
OUTERLAYER		
min track width & gap T/G	0.075 mm	0.065 mm
Cu foil thickness (min)	18 um	12 um
Cu foil thickness (max)	105 um	140 um
track width tolerance	+/- 10%	+/- 10%

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SOLDERMASK		
min clearance to copper (design)	50 um	40 um
min solder dam	100 um	75 um

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SURFACE FINISH		
Immersion Ni/Au	Y	Y
Immersion silver	Y	Y
Immersion tin	Y	Y
OSP	y	y
Pb-free HASL	Y	Y
Pb HASL	Y	Y
Electrolytic Hard gold	Y	Y

	current production capability	planned production capability
SCREEN PRINT		
peelable mask	Y	Y
carbon	Y	Y
via plugging	Y	Y
notation (legend)	Y	Y
notation - min line width	0.1 mm	0.1 mm

	current production capability	planned production capability
PROFILE		
rout min hole to edge (+/-)	0.1 mm	0.075 mm
scoring (V cut) location tolerance (+/-)	0.075 mm	0.05 mm
scoring (V cut) web thickness (1.6mm PCB)	0.4 mm	0.4 mm
scoring (V cut) web thickness tolerance (+/-)	+/- 10%	+/- 10%